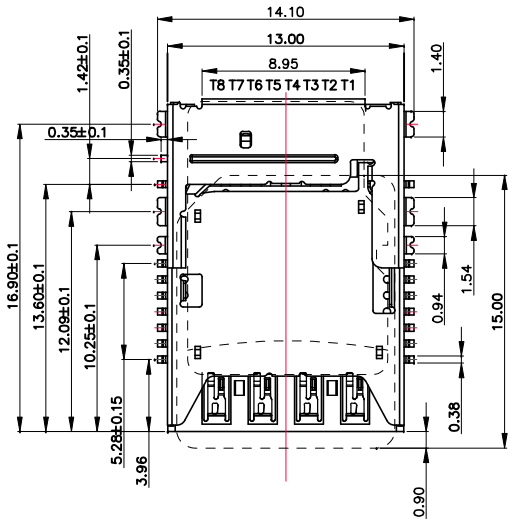
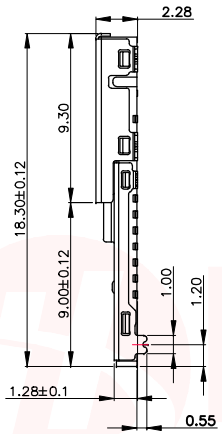
REV.	ECN NO OR DESCRIPTION	REVISED	DATE

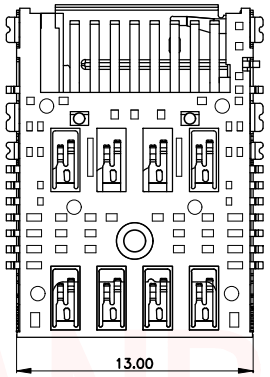
Pb Process Capable

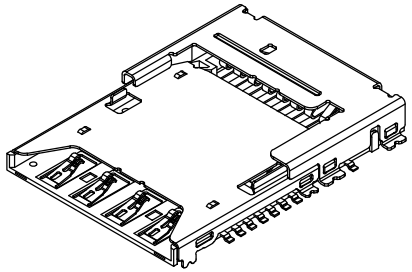
RoHS Compliant 2011/65/EU

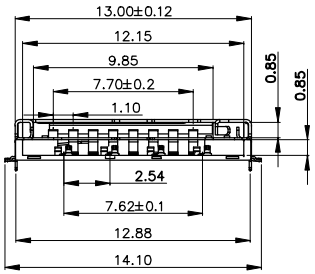
HALOGEN Compliant Halogen Free

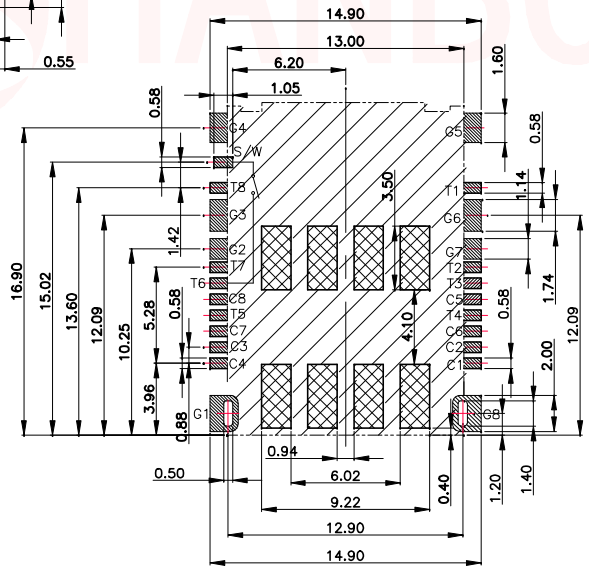












NOTE:

一.材质及电镀方式(MATERIAL AND FINISH)

1.塑胶(HOUSING): LCP,
UL 94V-0,COLOR: WHITE

2.端子(CONTACT): COPPER ALLOY
GOLD FLASH PLATING ON CONTACT AREA,
GOLD FLASH PLATING ON SOLDER TAILS
50u" NICKEL UNDER PLATING OVER ALL

3.铁壳(SHELL): SUS304-3/4H
40u" NICKEL UNDER PLATING OVER ALL

二.机械特性(MECHANICAL CHARACTERISTICS)

1.插入力(Insertion Force): 2.0Kgf Max

2.拔出力(Withdrawal Force): 0.1Kgf Min

3.耐久性(Durability): 5000次

三.电气特性

1.额定电流(Current rating): 1.0A AC/DC

2.接触电阻(Contact resistance): 100mΩ MAX

3.绝缘电阻(Insulation resistance): 500MΩ MIN

4.适用温度(Operating temperature): -20℃~65℃

TF CARD PIN ASSIGNMENT

PIN NO.	PIN ASSIGNMENT
T1	DAT2
T2	CD/DAT3 [2]
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DAT0
T8	DAT1

SIM pin assignment	
	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

NO PATTERN AREA
NO CIRCUIT AREA
SOLDER AREA

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

Circuit Diagram for Detect Switch of microSD card

WITHOUT CARD	OPEN	OPEN SW T6
INSERTING CARD	CLOSE	CLOSE SW T6

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: X :±0.35 X.X :±0.25 X.XX :±0.15

ANGLES: X :±2° X.X :±1°

东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO. , LTD

TITLE	NANO SIM+MICRO SD DUAL2IN1(COMBO)CARDCONN			
DWN	xiong	PART NO. MCS-104		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:1OF 1	REV: A4
CUSTOMER COPY				